Placement Accuracy ±0.02mm BGA rework station with Max PCB Size 570×480mm precise soldering and component repair solution WDS-750

Our Product Introduction

Basic Information

- Brand Name: Wisdomshow
- Certification: CE
- Model Number: WDS-750
- Minimum Order Quantity: 1
- Packaging Details: Wooden Case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200Sets / Month



Product Specification

- Power Supply: AC220V±10%, 50/60Hz
- Total Power: 7600W
- Thermocouple Ports: 4pcs
- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
- Placement Accuracy: ±0.02mm
- Chip Magnification: 2~32X
- Max PCB Size: 570×480mm
- Applicable Chip Size: 0.8×0.8mm – 80×80mm



More Images



for more products please visit us on bgaxraymachine.com

for more products please visit us on bgaxraymachine.com

Product Description

Product Description:

The Semi Automatic BGA Rework Station is a highly efficient and versatile tool designed for precise and reliable repair and rework of BGA (Ball Grid Array) components. Engineered to meet the demanding needs of modern electronics manufacturing and repair, this BGA rework station combines advanced technology with user-friendly features to deliver exceptional performance and accuracy.
One of the standout features of this BGA rework station is its capability to handle a maximum PCB size of 570*480mm, making it suitable for a wide range of circuit boards, from small to relatively large. This flexibility allows technicians to work on various electronic devices without any size constraints, enhancing productivity and convenience in the repair process.
The power supply for the unit operates at AC220V±10%, 50/60Hz, ensuring stable and consistent power delivery for optimal heating performance. With a total power consumption of 7600W, the station provides rapid heating and efficient thermal management, critical for successful BGA rework operations. The high power output supports the three heating zone design of the station, which is a key feature that distinguishes it from other rework stations.
The three heating zone configuration allows for precise temperature control across different sections of the PCB during the rework process. This multi-zone heating approach helps to evenly distribute heat, minimize thermal stress, and reduce the risk of damage to sensitive components and the PCB itself. By controlling the heating zones independently, the station ensures that the BGA chip and the surrounding board are heated uniformly and efficiently, resulting in better solder joint quality and higher reliability of the repaired device.
Designed to accommodate a wide range of chip sizes, the BGA rework station supports applicable chip dimensions from as small as 0.8*0.8mm up to 80*80mm. This broad compatibility makes it ideal for handling various BGA packages, including fine-pitch chips and larger components commonly found in modern electronics. Whether working on smartphones, computers, or industrial equipment, this station provides the adaptability needed for diverse repair tasks.
Another notable feature of the Semi Automatic BGA Rework Station is its chip magnification capability, ranging from 2 to 32 times. This magnification range allows technicians to closely inspect the chip and solder joints during the rework process, ensuring precise alignment and accurate placement of components. The enhanced visibility helps to detect any defects or misalignments early, improving the quality and success rate of rework operations.
Overall, the Semi Automatic BGA Rework Station is an indispensable tool for electronics repair professionals who require a reliable, high-performance solution for BGA rework. Its combination of a three heating zone system, large PCB capacity, wide chip size applicability, and adjustable magnification makes it a comprehensive and efficient choice for various applications. By investing in this advanced BGA rework station, technicians can achieve superior repair results with enhanced precision, reduced risk of damage, and increased operational efficiency.
In summary, this BGA rework station offers a perfect balance of power, precision, and versatility. The three heating zone design ensures optimal thermal control, the ability to handle a maximum PCB size of 570*480mm caters to diverse circuit boards, and the broad chip size compatibility from 0.8*0.8mm to 80*80mm covers a wide range of components. Coupled with the chip magnification range of 2~32X, this station provides the necessary tools for meticulous and effective BGA rework, making it a valuable asset in any electronics repair or manufacturing environment.

Features:

Product Name: Semi Automatic BGA Rework Station
Placement Accuracy: ±0.02mm for precise component positioning
Power Supply: AC220V±10%, 50/60Hz
Max PCB Size: 570*480mm, suitable for various motherboard repair tasks
Thermocouple Ports: 4pcs for accurate temperature monitoring
Total Power: 7600W for efficient hot air heating
Ideal for motherboard repair and CPU repair applications
Advanced hot air heating system ensures uniform temperature distribution
Semi-automatic operation improves rework efficiency and accuracy

Technical Parameters:

Placement Accuracy	±0.02mm
Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
Max PCB Size	570*480mm
Chip Magnification	2~32X
Thermocouple Ports	4pcs
Power Supply	AC220V±10%, 50/60Hz
Total Power	7600W
Applicable Chip Size	0.8*0.8mm – 80*80mm

Applications:

The Wisdomshow WDS-750 Semi Automatic BGA Rework Station is an advanced solution designed for precision and efficiency in

electronic repair and manufacturing environments. Originating from Shenzhen, China, this CE-certified device is ideal for applications requiring meticulous rework and soldering of Ball Grid Array (BGA) components. Its semi automatic operation allows technicians to perform complex tasks with enhanced control and accuracy, making it suitable for both small-scale repairs and medium-sized production lines.

One of the standout features of the WDS-750 is its versatile compatibility with chip sizes ranging from 0.8*0.8mm up to 80*80mm. This broad range ensures that users can handle a wide variety of BGA packages commonly found in smartphones, laptops, gaming consoles, and other high-tech electronic devices. The station's maximum PCB size of 570*480mm accommodates large circuit boards, providing flexibility for diverse repair scenarios.

The rework station integrates a hot air heating system that delivers consistent and controlled thermal energy, essential for safely melting solder without damaging the delicate components. Complementing this is the infrared preheating table, which ensures uniform temperature distribution across the PCB before rework begins, reducing thermal stress and improving solder joint reliability. These combined heating technologies optimize the reflow process and minimize the risk of component warping or PCB delamination.

Precision is paramount in BGA rework, and the Wisdomshow WDS-750 excels with its placement accuracy of ±0.02mm. This level of precision is further enhanced by the 2~32X chip magnification feature, allowing technicians to visually inspect and accurately position chips during the rework process. Additionally, the station is equipped with four thermocouple ports to monitor and control temperature zones effectively, ensuring a stable thermal profile throughout the operation.

For businesses and repair shops, the WDS-750 offers a reliable supply ability of 200 sets per month, with a minimum order quantity of just one unit. The product is securely packaged in a wooden case to ensure safe delivery, which typically occurs within 3-5 days. Payment terms are flexible with TT accepted, making procurement straightforward and efficient.

In summary, the Wisdomshow WDS-750 Semi Automatic BGA Rework Station is perfectly suited for various application occasions and scenarios, including electronics repair centers, quality control labs, prototype development, and small to medium manufacturing setups. Its combination of semi automatic operation, hot air heating, and infrared preheating table makes it an indispensable tool for precise, high-quality BGA rework tasks.

Shenzhen Wisdomshow Technology Co.,ltd

+86 18926538696 elysia.li@wdsbga.cn bgaxraymachine.com

No. 3 Kangtai 3rd Road, Shatou Community, Shajing Street, Bao'an District, Shenzhen, China